IEC 62137
(First edition – 2004)

ENVIRONMENTAL AND ENDURANCE TESTING – TEST METHODS FOR SURFACE-MOUNT BOARDS OF AREA ARRAY TYPE PACKAGES FBGA, BGA, FLGA, LGA, SON AND QFN

CORRIGENDUM 1

Page 5

2 Normative references

Delete:

IEC 61190-1-1, *Attachment materials for electronic assemblies – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 61190-1-2, *Attachment materials for electronic assemblies – Part 1-2: Requirements for solder pastes for high-quality interconnections in electronics assembly*

IEC 61190-1-3, *Attachment materials for electronic assemblies – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

Withdrawn
iTeh Standards
(https://standards.iteh.ai)
Document Preview

Page 16

A.2.4.4 Post-treatment (flux removal)

IEC 62137:2004/COR1:2005
https://standards.iteh.ai/catalog/standards/iec/75cc38f1-aa07-454e-bf31-54905617ef5a/iec-62137-2004-cor1-2005

First sentence

Instead of:

"(propanol)"

read:

"(isopropanol)".

Page 17

A.3.4.1 Soldering process, a) Pre-treatment

Instead of:

"as specified in Figure 3"

read:

"as specified in Figure 2".